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HITA-0335

30978 U.S. PTO
10/346097
01/17/03

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of Conveying Party(ies):

Toshio SASAKI and Toshio YAMADA

Additional names of conveying parties attached: Yes ☐ No ☒

2. Name and Address of Receiving Party(ies):

Name: **Hitachi, Ltd.**

Address: 6, Kanda Surugadai 4-chome
Chiyoda-ku, Tokyo, Japan

3. Nature of Conveyance:

☒ Assignment Merger
 Security Agreement Change of Name

Other:

Execution Date: **December 2, 2002**

4. (a) Patent Application Number(s):

If this document is being filed together with a new application,
the execution date of the application is:

Additional Numbers Attached:

4. (b) Patent Numbers:

10/346097

5. Name and Address of Party to whom Correspondence
Concerning this Document Should be Mailed:

Name: **Stanley P. Fisher**

Address: **Reed Smith LLP**
3100 Fairview Park Dr.
Suite 1400
Falls Church, Va. 22042

6. Total Number of Applications and Patents Involved: 1

7. Total Fee: **\$40.00**
(37 C.F.R. § 3.41)

☒ Enclosed.
☒ Authorized to be charged to deposit account.

8. Deposit Account Number: **08-1480**

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9. Statement and Signature:

To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document.

Stanley P. Fisher, Registration No. 24, 344

January 17, 2003
Juan Carlos A. Marquez, Registration No. 34,072

Total number of pages comprising cover sheet: 1

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ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR INTEGRATED CIRCUIT AND METHOD OF MANUFACTURING OF SEMICONDUCTOR INTEGRATED CIRCUIT

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner-ship of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

| | | |
|-----|-------------------------------|-----------------|
| 1) | Toshio Sasaki (Toshio SASAKI) | 2/December/2002 |
| 2) | Toshio Yamada (Toshio YAMADA) | 2/December/2002 |
| 3) | | |
| 4) | | |
| 5) | | |
| 6) | | |
| 7) | | |
| 8) | | |
| 9) | | |
| 10) | | |